	Package PQFP208 (28x28)	MDS 744
---	-----------------------------------	--------------------------

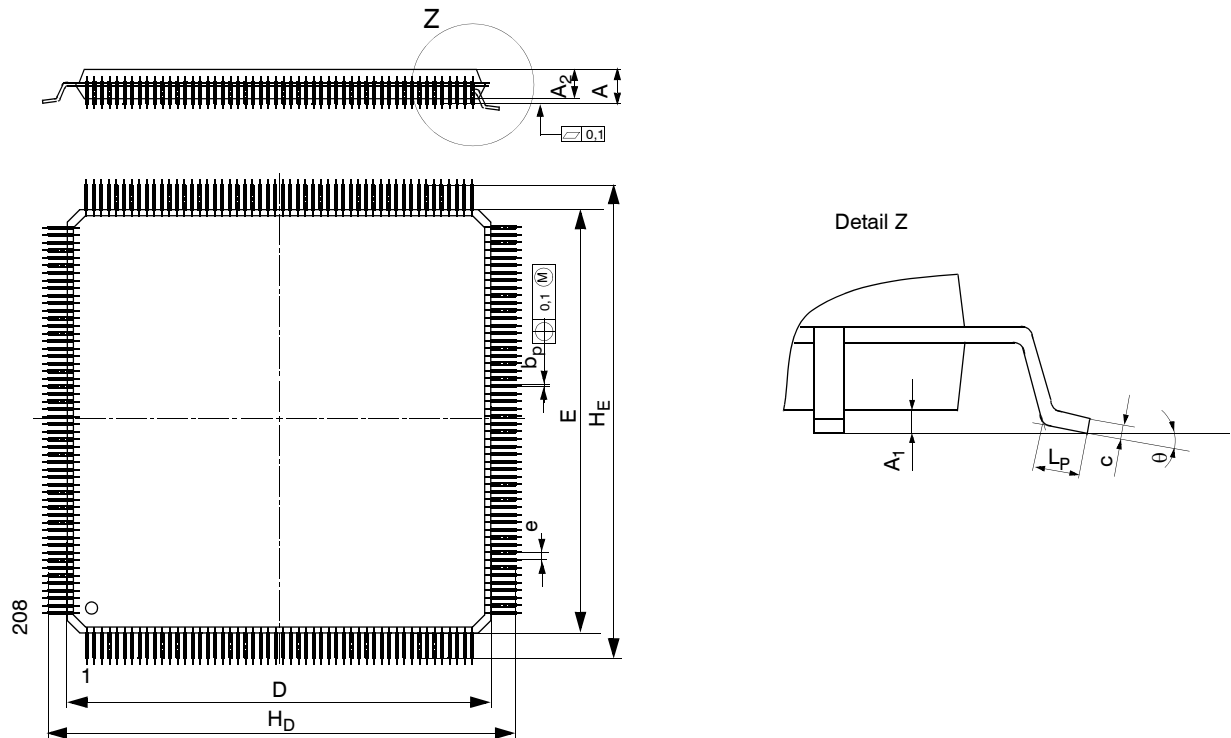
Supersedes
July 1997

Dimensions in millimetres

1. Amendment November 1997

Based on JEDEC JEP95: MO-108 and MS-022

Dimension



Dimensions of Sub-Group B1	
e_{nom}	0,50
A_{max}	4,07
b_{Pmin}	0,13
b_{Pmax}	0,25
H_{Emin}	30,95
H_{Emax}	31,45
H_{Dmin}	30,95
H_{Dmax}	31,45
L_{Pmin}	0,65

Weight $\leq 5,3$ g

Package Body Material Low Stress Epoxy

Lead Material FeNi-Alloy or Cu-Alloy

Lead Finish solder plating

Lead Form Z-bends

Dimensions of Sub-Group C1	
A_{min}	3,70
A_{1min}	0,25
A_{1max}	0,50
A_{2min}	3,20
A_{2max}	3,60
c_{min}	0,12
c_{max}	0,23
D_{min}	27,90
D_{max}	28,10
E_{min}	27,90
E_{max}	28,10
θ_{min}	0°
θ_{max}	10°

Zentrum Mikroelektronik Dresden AG

Editor: signed Schoder

Date: 04.12.2001

Check: signed Marx

Quality: signed Lorenz

Doc-No.
QS-000744-HD-02